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## Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

### Details

Product Status	Obsolete
Number of LABs/CLBs	8375
Number of Logic Elements/Cells	67000
Total RAM Bits	4642816
Number of I/O	416
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	900-BBGA
Supplier Device Package	900-FPBGA (31x31)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m70se-5f900i">https://www.e-xfl.com/product-detail/lattice-semiconductor/lfe2m70se-5f900i</a>

## Architecture Overview

Each LatticeECP2/M device contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM™ Embedded Block RAM (EBR) and rows of sys-DSP™ Digital Signal Processing blocks, as shown in Figure 2-1. In addition, the LatticeECP2M family contains SERDES Quads in one or more of the corners. Figure 2-2 shows the block diagram of ECP2M20 with one quad.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional Unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM and ROM functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row.

The LatticeECP2/M devices contain one or more rows of sysMEM EBR blocks. sysMEM EBRs are large dedicated 18K fast memory blocks. Each sysMEM block can be configured in a variety of depths and widths of RAM or ROM. In addition, LatticeECP2/M devices contain up to two rows of DSP Blocks. Each DSP block has multipliers and adder/accumulators, which are the building blocks for complex signal processing capabilities.

The LatticeECP2M devices feature up to 16 embedded 3.125Gbps SERDES (Serializer / Deserializer) channels. Each SERDES channel contains independent 8b/10b encoding / decoding, polarity adjust and elastic buffer logic. Each group of four SERDES channels along with its Physical Coding Sub-layer (PCS) block, creates a quad. The functionality of the SERDES/PCS Quads can be controlled by memory cells set during device configuration or by registers that are addressable during device operation. The registers in every quad can be programmed by a soft IP interface, referred to as the SERDES Client Interface (SCI). These quads (up to four) are located at the corners of the devices.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysI/O buffers. The sysI/O buffers of the LatticeECP2/M devices are arranged in eight banks, allowing the implementation of a wide variety of I/O standards. In addition, a separate I/O bank is provided for the programming interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. The PIC logic also includes pre-engineered support to aid in the implementation of high speed source synchronous standards such as SPI4.2, along with memory interfaces including DDR2.

The LatticeECP2/M registers in PFU and sysI/O can be configured to be SET or RESET. After power up and the device is configured, it enters into user mode with these registers SET/RESET according to the configuration setting, allowing the device entering to a known state for predictable system function.

Other blocks provided include PLLs, DLLs and configuration functions. The LatticeECP2/M architecture provides two General PLLs (GPLL) and up to six Standard PLLs (SPLL) per device. In addition, each LatticeECP2/M family member provides two DLLs per device. The GPLLs and DLLs blocks are located in pairs at the end of the bottom-most EBR row; the DLL block is located towards the edge of the device. The SPLL blocks are located at the end of the other EBR/DSP rows.

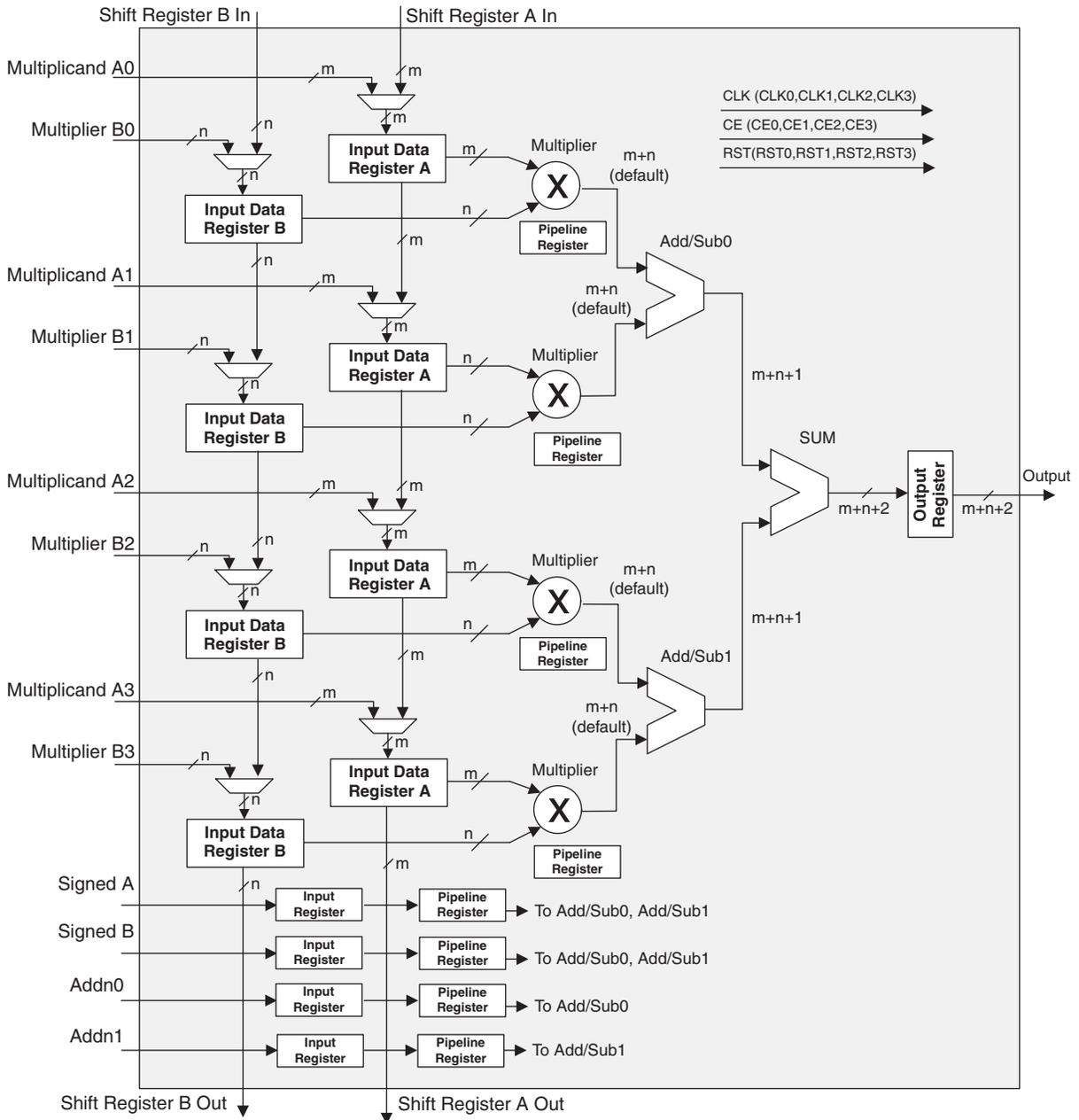
The configuration block that supports features such as configuration bit-stream decryption, transparent updates and dual boot support is located toward the center of this EBR row. The Ball Grid Array (BGA) package devices in the LatticeECP2/M family supports a sysCONFIG™ port located in the corner between banks four and five, which allows for serial or parallel device configuration.

In addition, every device in the family has a JTAG port. This family also provides an on-chip oscillator. The LatticeECP2/M devices use 1.2V as their core voltage.

### MULTADDSUBSUM sysDSP Element

In this case, the operands A0 and B0 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A1 and B1. Additionally the operands A2 and B2 are multiplied and the result is added/subtracted with the result of the multiplier operation of operands A3 and B3. The result of both addition/subtraction are added in a summation block. The user can enable the input, output and pipeline registers. Figure 2-26 shows the MULTADDSUBSUM sysDSP element.

Figure 2-26. MULTADDSUBSUM



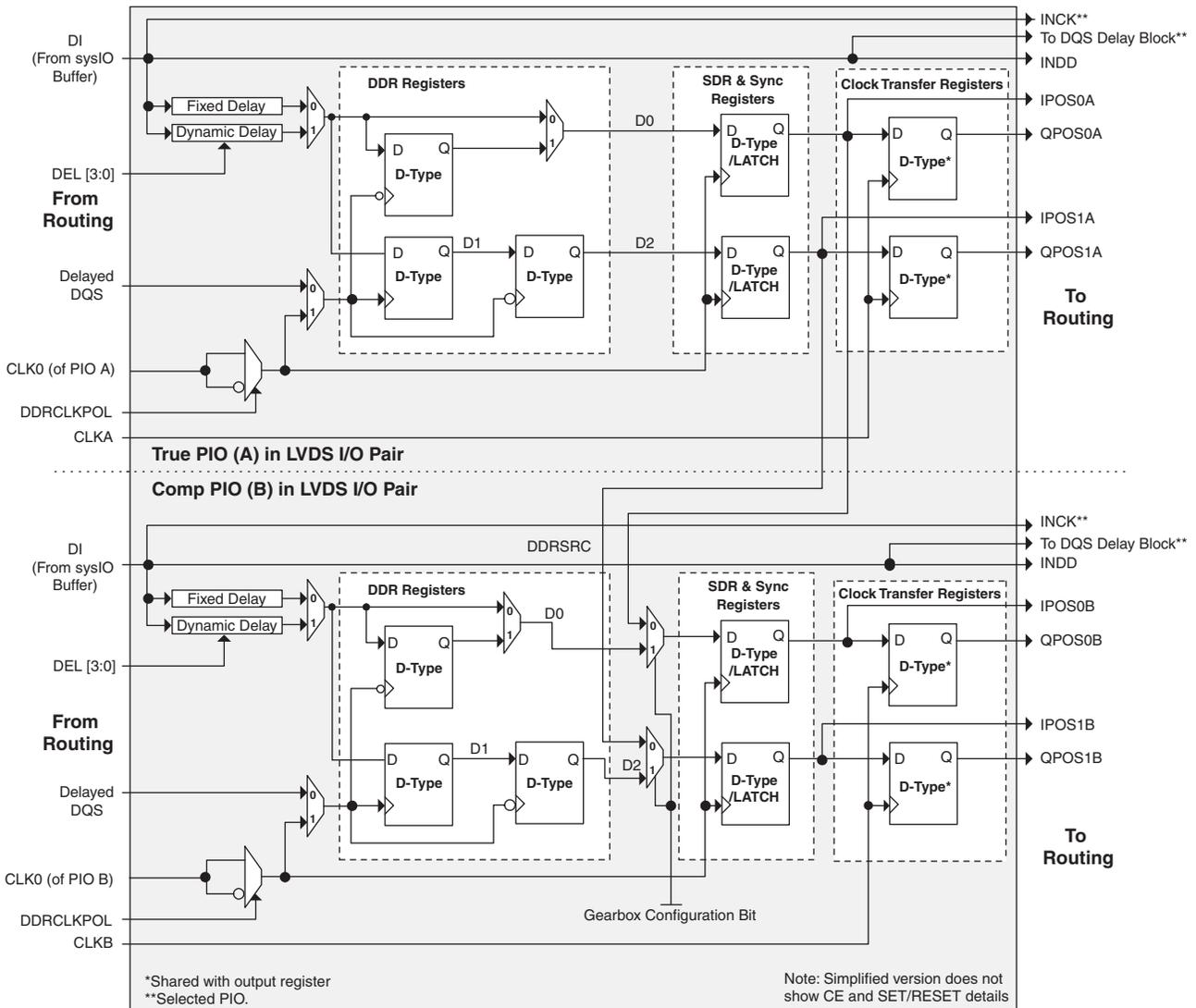
### Clock, Clock Enable and Reset Resources

Global Clock, Clock Enable and Reset signals from routing are available to every DSP block. Four Clock, Reset and Clock Enable signals are selected for the sysDSP block. From four clock sources (CLK0, CLK1, CLK2, CLK3)

By combining input blocks of the complementary PIOs and sharing some registers from output blocks, a gearbox function can be implemented, which takes a double data rate signal applied to PIOA and converts it as four data streams, IPOS0A, IPOS1A, IPOS0B and IPOS1B. Figure 2-29 shows the diagram using this gearbox function. For more information about this topic, please see information regarding additional documentation at the end of this data sheet.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to the system clock domain. For further information about this topic, see the DDR Memory section of this data sheet.

**Figure 2-29. Input Register Block for Left, Right and Bottom Edges**

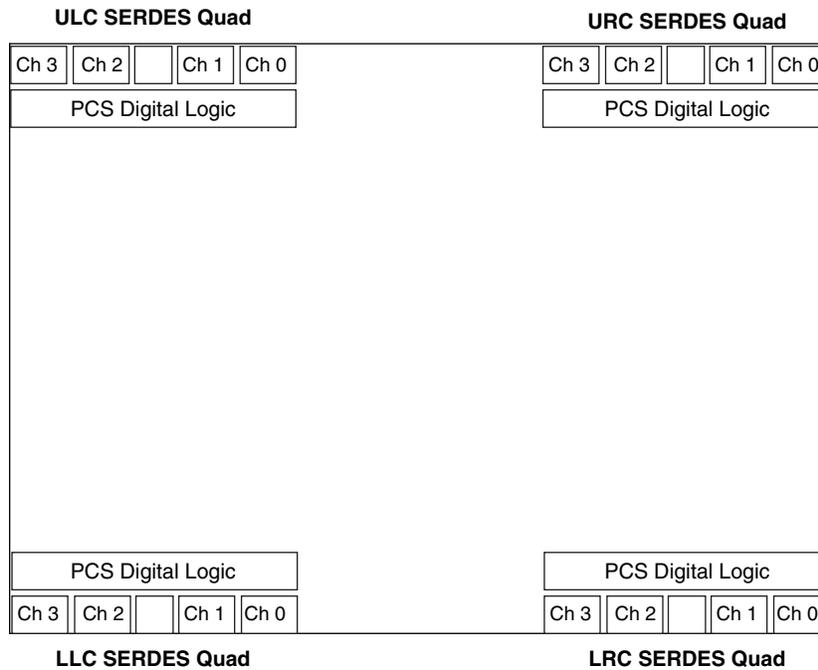


## SERDES and PCS (Physical Coding Sublayer)

LatticeECP2M devices feature up to 16 channels of embedded SERDES arranged in quads at the corners of the devices. Figure 2-39 shows the position of the quad blocks in relation to the PFU array for LatticeECP2M70 and LatticeECP2M100 devices. Table 2-15 shows the location of Quads for all the devices.

Each quad contains four dedicated SERDES (Ch0 to Ch3) for high-speed, full-duplex serial data transfer. Each quad also has a PCS block that interfaces to the SERDES channels and contains digital logic to support an array of popular data protocols. PCS also contains logic to the interface to FPGA core.

**Figure 2-39. SERDES Quads (LatticeECP2M70/LatticeECP2M100)**



**Table 2-15. Available SERDES Quads per LatticeECP2M Devices**

Device	URC Quad	ULC Quad	LRC Quad	LLC Quad
ECP2M20	Available	—	—	—
ECP2M35	Available	—	—	—
ECP2M50	Available	—	Available	—
ECP2M70	Available	Available	Available	Available
ECP2M100	Available	Available	Available	Available

### SERDES Block

A differential receiver receives the serial encoded data stream, equalizes the signal, extracts the buried clock and de-serializes the data-stream before passing the 8- or 10-bit data to the PCS logic. The transmit channel receives the parallel (8- or 10-bit) encoded data, serializes the data and transmits the serial bit stream through the differential buffers. There is a single transmit clock per quad. Figure 2-40 shows a single channel SERDES and its interface to the PCS logic. Each SERDES receiver channel provides a recovered clock to the PCS block and to the FPGA core logic.

## DC Electrical Characteristics

### Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{IL}, I_{IH}^{1,2}$	Input or I/O Low Leakage	$0 \leq V_{IN} \leq (V_{CCIO} - 0.2V)$	—	—	10	$\mu A$
$I_{IH}^{1,3}$	Input or I/O High Leakage	$(V_{CCIO} - 0.2V) < V_{IN} \leq 3.6V$	—	—	150	$\mu A$
$I_{PU}$	I/O Active Pull-up Current	$0 \leq V_{IN} \leq 0.7 V_{CCIO}$	-30	—	-210	$\mu A$
$I_{PD}$	I/O Active Pull-down Current	$V_{IL} (MAX) \leq V_{IN} \leq V_{IH} (MAX)$	30	—	210	$\mu A$
$I_{BHLS}$	Bus Hold Low Sustaining Current	$V_{IN} = V_{IL} (MAX)$	30	—	—	$\mu A$
$I_{BHHS}$	Bus Hold High Sustaining Current	$V_{IN} = 0.7 V_{CCIO}$	-30	—	—	$\mu A$
$I_{BHLO}$	Bus Hold Low Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	210	$\mu A$
$I_{BHHO}$	Bus Hold High Overdrive Current	$0 \leq V_{IN} \leq V_{CCIO}$	—	—	-210	$\mu A$
$V_{BHT}$	Bus Hold Trip Points	$0 \leq V_{IN} \leq V_{IH} (MAX)$	$V_{IL} (MAX)$	—	$V_{IH} (MIN)$	V
$C1^4$	I/O Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	8	pf
$C2^4$	Dedicated Input Capacitance	$V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V,$ $V_{CC} = 1.2V, V_{IO} = 0 \text{ to } V_{IH} (MAX)$	—	5	6	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. When used as  $V_{REF}$  maximum leakage = 25uA
3. Applicable to general purpose I/Os in top and bottom banks.
4.  $T_A$  25°C,  $f = 1.0MHz$ .

**LatticeECP2 Supply Current (Standby)<sup>1, 2, 3, 4</sup>**
**Over Recommended Operating Conditions**

Symbol	Parameter	Device	Typ. <sup>5</sup>	Units
I <sub>CC</sub>	Core Power Supply Current	ECP2-6	10	mA
		ECP2-12	20	mA
		ECP2-20	30	mA
		ECP2-35	50	mA
		ECP2-50	70	mA
		ECP2-70	100	mA
I <sub>CCAUX</sub>	Auxiliary Power Supply Current	ECP2-6	24	mA
		ECP2-12	24	mA
		ECP2-20	24	mA
		ECP2-35	24	mA
		ECP2-50	24	mA
		ECP2-70	24	mA
I <sub>CCGPLL</sub>	GPLL Power Supply Current (per GPLL)	ECP2-35, -50, -70 Only	0.5	mA
I <sub>CCSPLL</sub>	GPLL Power Supply Current (per SPLL)	ECP2-35, -50, -70 Only	0.5	mA
I <sub>CCIO</sub>	Bank Power Supply Current (Per Bank)	ECP2-6	2	mA
		ECP2-12	2	mA
		ECP2-20	2	mA
		ECP2-35	2	mA
		ECP2-50	2	mA
		ECP2-70	2	mA
I <sub>CCJ</sub>	VCCJ Power Supply Current	All Devices	3	mA

1. For further information about supply current, please see the list of additional technical documentation at the end of this data sheet.
2. Assumes all outputs are tristated, all inputs are configured as LVCMOS and held at the V<sub>CCIO</sub> or GND.
3. Frequency 0MHz.
4. Pattern represents a "blank" configuration data file.
5. T<sub>J</sub> = 25°C, power supplies at normal voltage.

### LVDS25E

The top and bottom sides of LatticeECP2/M devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

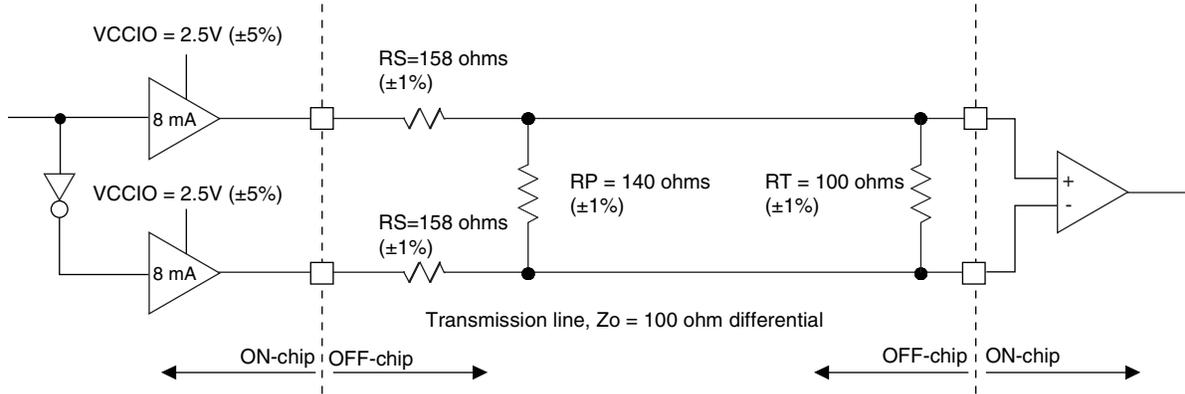


Table 3-2. LVDS25E DC Conditions

Parameter	Description	Typical	Units
V <sub>CCIO</sub>	Output Driver Supply (+/-5%)	2.50	V
Z <sub>OUT</sub>	Driver Impedance	20	Ω
R <sub>S</sub>	Driver Series Resistor (+/-1%)	158	Ω
R <sub>P</sub>	Driver Parallel Resistor (+/-1%)	140	Ω
R <sub>T</sub>	Receiver Termination (+/-1%)	100	Ω
V <sub>OH</sub>	Output High Voltage	1.43	V
V <sub>OL</sub>	Output Low Voltage	1.07	V
V <sub>OD</sub>	Output Differential Voltage	0.35	V
V <sub>CM</sub>	Output Common Mode Voltage	1.25	V
Z <sub>BACK</sub>	Back Impedance	100.5	Ω
I <sub>DC</sub>	DC Output Current	6.03	mA

### LVCMOS33D

All I/O banks support emulated differential I/O using the LVCMOS33D I/O type. This option, along with the external resistor network, provides the system designer the flexibility to place differential outputs on an I/O bank with 3.3V VCCIO. The default drive current for LVCMOS33D output is 12mA with the option to change the device strength to 4mA, 8mA, 16mA or 20mA. Follow the LVCMOS33 specifications for the DC characteristics of the LVCMOS33D.

## SERDES High-Speed Data Transmitter (LatticeECP2M Family Only)<sup>1, 2</sup>

Table 3-7. Serial Output Timing and Levels

Symbol	Description	Frequency	Min.	Typ.	Max.	Units
V <sub>TX-DIFF-P-P-1</sub>	Differential swing (1V setting) <sup>1, 2</sup>	0.25 to 3.125 Gbps	0.79	0.99	1.19	V, p-p
V <sub>TX-DIFF-P-P-1.25</sub>	Differential swing (1.25V setting) <sup>1, 2</sup>	0.25 to 3.125 Gbps	1.00	1.25	1.50	V, p-p
V <sub>TX-DIFF-P-P-1.3</sub>	Differential swing (1.3V setting) <sup>1, 2</sup>	0.25 to 3.125 Gbps	1.04	1.30	1.56	V, p-p
V <sub>TX-DIFF-P-P-1.35</sub>	Differential swing (1.35V setting) <sup>1, 2</sup>	0.25 to 3.125 Gbps	1.08	1.35	1.62	V, p-p
V <sub>OCM</sub>	Output common mode voltage	—	V <sub>CCOB</sub> - 0.75	V <sub>CCOB</sub> - 0.60	V <sub>CCOB</sub> - 0.45	V
T <sub>TX-R</sub>	Rise time (20% to 80%)	—	—	70	—	ps
T <sub>TX-F</sub>	Fall time (80% to 20%)	—	—	70	—	ps
Z <sub>TX-OI-SE</sub>	Output impedance 50/75/HiZ K Ohms (single-ended)	—	—	50/70 HiZ	—	Ohms
R <sub>TX-RL</sub>	Return loss (with package)	—	—	9	—	dB

1. All measurements are with 50 ohm impedance.

2. See TN1124, [LatticeECP2M SERDES/PCS Usage Guide](#) for actual binary settings.

Table 3-8. Channel Output Jitter - x10 Mode

Description	Frequency	Min.	Typ.	Max.	Units
Deterministic	3.125 Gbps	—	0.08	0.12	UI, p-p
Random	3.125 Gbps	—	0.22	0.38	UI, p-p
Total	3.125 Gbps	—	0.33	0.43	UI, p-p
Deterministic	2.5 Gbps	—	0.08	0.17	UI, p-p
Random	2.5 Gbps	—	0.20	0.25	UI, p-p
Total	2.5 Gbps	—	0.25	0.35	UI, p-p
Deterministic	1.25 Gbps	—	0.03	0.10	UI, p-p
Random	1.25 Gbps	—	0.14	0.19	UI, p-p
Total	1.25 Gbps	—	0.17	0.24	UI, p-p
Deterministic	250 Mbps	—	0.04	0.17	UI, p-p
Random	250 Mbps	—	0.12	0.13	UI, p-p
Total	250 Mbps	—	0.15	0.29	UI, p-p

Note: Values are measured with PRBS 2<sup>7</sup>-1, all channels operating, FPGA Logic active, I/Os around SERDES pins quiet, reference clock at x10 mode.

**LFE2-6E/SE and LFE2-12E/SE Logic Signal Connections: 144 TQFP (Cont.)**

LFE2-6E/SE					LFE2-12E/12SE			
Pin Number	Pin/Pad Function	Bank	Dual Function	Differential	Pin/Pad Function	Bank	Dual Function	Differential
46	NC	5			PB16B	5	BDQ15	C
47	GND	-			GND	-		
48	VCC				VCC	-		
49	PB8A	5	PCLKT5_0/BDQ6	T	PB26A	5	PCLKT5_0/BDQ24	T
50	PB8B	5	PCLKC5_0/BDQ6	C	PB26B	5	PCLKC5_0/BDQ24	C
51	GND	-			GND	-		
52	PB13A	4	PCLKT4_0/BDQ15	T	PB31A	4	PCLKT4_0/BDQ33	T
53	PB13B	4	PCLKC4_0/BDQ15	C	PB31B	4	PCLKC4_0/BDQ33	C
54	VCC	-			VCC	-		
55	PB14A	4	BDQ15	T	PB34A	4	BDQ33	T
56	PB14B	4	BDQ15	C	PB34B	4	BDQ33	C
57	PB16A	4	BDQ15	T	PB40A	4	BDQ42	T
58	PB16B	4	BDQ15	C	PB40B	4	BDQ42	C
59	PB18A	4	BDQ15	T	PB44A	4	BDQ42	T
60	PB18B	4	BDQ15	C	PB44B	4	BDQ42	C
61	GND	-			GND	-		
62	PB20A	4	BDQ24	T	PB48A	4	BDQ51	T
63	PB20B	4	BDQ24	C	PB48B	4	BDQ51	C
64	VCCIO4	4			VCCIO4	4		
65	PB22A	4	BDQ24	T	PB50A	4	BDQ51	T
66	PB22B	4	BDQ24	C	PB50B	4	BDQ51	C
67	PB24A	4	BDQS24	T	PB52A	4	BDQ51	T
68	PB24B	4	BDQ24	C	PB52B	4	BDQ51	C
69	PB26A	4	BDQ24	T	PB54A	4	BDQ51	T
70	PB26B	4	BDQ24	C	PB54B	4	BDQ51	C
71	PB28A	4	VREF2_4/BDQ24	T	PB55A	4	VREF2_4/BDQ51	T
72	PB28B	4	VREF1_4/BDQ24	C	PB55B	4	VREF1_4/BDQ51	C
73	CFG1	8			CFG1	8		
74	CFG2	8			CFG2	8		
75	PROGRAMN	8			PROGRAMN	8		
76	INITN	8			INITN	8		
77	CFG0	8			CFG0	8		
78	CCLK	8			CCLK	8		
79	DONE	8			DONE	8		
80	PR29A	8	D0/SPIFASTN		PR29A	8	D0/SPIFASTN	
81	GND	-			GND	-		
82	PR26A	8	D6		PR26A	8	D6	
83	VCC	-			VCC	-		
84	PR25B	8	D7/SPID0	C	PR25B	8	D7/SPID0	C
85	VCCIO8	8			VCCIO8	8		
86	PR25A	8	DI/CSSPION	T	PR25A	8	DI/CSSPION	T
87	PR24B	8	DOUT/CSON	C	PR24B	8	DOUT/CSON	C
88	PR24A	8	BUSY/SISPI	T	PR24A	8	BUSY/SISPI	T
89	VCCIO3	3			VCCIO3	3		
90	VCCAUX	-			VCCAUX	-		

**LFE2-20E/SE and LFE2-35E/SE Logic Signal Connections: 672 fpBGA**  
**(Cont.)**

LFE2-20E/20SE					LFE2-35E/35SE			
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
GND	GNDIO5	-			GNDIO5	-		
W10	PB11A	5	BDQ15	T	PB11A	5	BDQ15	T
Y10	PB11B	5	BDQ15	C	PB11B	5	BDQ15	C
W11	PB12A	5	BDQ15	T	PB12A	5	BDQ15	T
AA10	PB12B	5	BDQ15	C	PB12B	5	BDQ15	C
AC8	PB13A	5	BDQ15	T	PB13A	5	BDQ15	T
AD8	PB13B	5	BDQ15	C	PB13B	5	BDQ15	C
VCCIO	VCCIO5	5			VCCIO5	5		
AB8	PB14A	5	BDQ15	T	PB14A	5	BDQ15	T
AB10	PB14B	5	BDQ15	C	PB14B	5	BDQ15	C
GND	GNDIO5	-			GNDIO5	-		
AE6	PB15A	5	BDQS15	T	PB15A	5	BDQS15	T
AF6	PB15B	5	BDQ15	C	PB15B	5	BDQ15	C
AA11	PB16A	5	BDQ15	T	PB16A	5	BDQ15	T
AC9	PB16B	5	BDQ15	C	PB16B	5	BDQ15	C
AB9	PB17A	5	BDQ15	T	PB17A	5	BDQ15	T
AD9	PB17B	5	BDQ15	C	PB17B	5	BDQ15	C
VCCIO	VCCIO5	5			VCCIO5	5		
Y11	PB18A	5	BDQ15	T	PB18A	5	BDQ15	T
AB11	PB18B	5	BDQ15	C	PB18B	5	BDQ15	C
AE7	PB19A	5	BDQ15	T	PB19A	5	BDQ15	T
AF7	PB19B	5	BDQ15	C	PB19B	5	BDQ15	C
GND	GNDIO5	-			GNDIO5	-		
AC10	PB20A	5	BDQ24	T	PB20A	5	BDQ24	T
AD10	PB20B	5	BDQ24	C	PB20B	5	BDQ24	C
AA12	PB21A	5	BDQ24	T	PB21A	5	BDQ24	T
W12	PB21B	5	BDQ24	C	PB21B	5	BDQ24	C
AB12	PB22A	5	BDQ24	T	PB22A	5	BDQ24	T
VCCIO	VCCIO5	5			VCCIO5	5		
Y12	PB22B	5	BDQ24	C	PB22B	5	BDQ24	C
AD12	PB23A	5	BDQ24	T	PB23A	5	BDQ24	T
AC12	PB23B	5	BDQ24	C	PB23B	5	BDQ24	C
AC13	PB24A	5	BDQS24	T	PB24A	5	BDQS24	T
GND	GNDIO5	-			GNDIO5	-		
AA13	PB24B	5	BDQ24	C	PB24B	5	BDQ24	C
AD13	PB25A	5	BDQ24	T	PB25A	5	BDQ24	T
AC14	PB25B	5	BDQ24	C	PB25B	5	BDQ24	C
AE8	PB26A	5	BDQ24	T	PB26A	5	BDQ24	T
VCCIO	VCCIO5	5			VCCIO5	5		
AF8	PB26B	5	BDQ24	C	PB26B	5	BDQ24	C
AB15	PB27A	5	BDQ24	T	PB27A	5	BDQ24	T
Y13	PB27B	5	BDQ24	C	PB27B	5	BDQ24	C
AE9	PB28A	5	BDQ24	T	PB28A	5	BDQ24	T
GND	GNDIO5	-			GNDIO5	-		
AF9	PB28B	5	BDQ24	C	PB28B	5	BDQ24	C
W13	PB29A	5	BDQ33	T	PB29A	5	BDQ33	T

**LFE2-70E/SE Logic Signal Connections: 900 fpBGA (Cont.)**

LFE2-70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
C5	PT11B	0		C
D5	PT11A	0		T
E9	PT10B	0		C
G9	PT10A	0		T
GND	GNDIO0	-		
B10	PT9B	0		C
A10	PT9A	0		T
D9	PT8B	0		C
C9	PT8A	0		T
VCCIO	VCCIO0	0		
F9	PT7B	0		C
H9	PT7A	0		T
B9	PT6B	0		C
A9	PT6A	0		T
GND	GNDIO0	-		
E8	PT5B	0		C
G8	PT5A	0		T
A8	PT4B	0		C
B8	PT4A	0		T
VCCIO	VCCIO0	0		
F8	PT3B	0		C
F7	PT3A	0		T
J10	PT2B	0	VREF2_0	C
J9	PT2A	0	VREF1_0	T
AA11	VCC	-		
AA20	VCC	-		
K11	VCC	-		
K21	VCC	-		
K22	VCC	-		
L11	VCC	-		
L12	VCC	-		
L13	VCC	-		
L18	VCC	-		
L19	VCC	-		
L20	VCC	-		
M11	VCC	-		
M20	VCC	-		
N11	VCC	-		
N20	VCC	-		
V11	VCC	-		
V20	VCC	-		
W11	VCC	-		
W20	VCC	-		

## LFE2M-20E/SE and LFE2M-35E/SE Logic Signal Connections: 256 fpBGA (Cont.)

LFE2M20E/SE					LFE2M35E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
A3	GND	-			GND	-			
A9	GND	-			GND	-			
B12	GND	-			GND	-			
B6	GND	-			GND	-			
E15	GND	-			GND	-			
E2	GND	-			GND	-			
H14	GND	-			GND	-			
H8	GND	-			GND	-			
H9	GND	-			GND	-			
J3	GND	-			GND	-			
J8	GND	-			GND	-			
J9	GND	-			GND	-			
M15	GND	-			GND	-			
M2	GND	-			GND	-			
P9	GND	-			GND	-			
R12	GND	-			GND	-			
R5	GND	-			GND	-			
T1	GND	-			GND	-			
T16	GND	-			GND	-			
D10	NC	-			NC	-			
D11	NC	-			NC	-			
D12	NC	-			NC	-			
D13	NC	-			NC	-			
D14	NC	-			NC	-			
D4	NC	-			NC	-			
D5	NC	-			NC	-			
D6	NC	-			NC	-			
D7	NC	-			NC	-			
E11	NC	-			NC	-			
E6	NC	-			NC	-			
E8	NC	-			NC	-			
E9	NC	-			NC	-			
F10	NC	-			NC	-			
F7	NC	-			NC	-			
F8	NC	-			NC	-			
F9	NC	-			NC	-			

\* Supports true LVDS. Other differential signals must be emulated with external resistors.

\*\* These dedicated input pins can be used for GPLLs or GDLLs within the respective quadrant.

\*\*\*Due to packaging bond out option, this DQS does not have all the necessary DQ pins bonded out for a full 8-bit data width.

Note: VCCIO and GND pads are used to determine the average DC current drawn by I/Os between GND/VCCIO connections, or between the last GND/VCCIO in an I/O bank and the end of an I/O bank. The substrate pads listed in the Pin Table do not necessarily have a one to one connection with a package ball or pin.

**LFE2M20E/SE and LFE2M35E/SE Logic Signal Connections: 484 fpBGA**  
**(Cont.)**

LFE2M20E/SE					LFE2M35E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
L4	PL24B	7	LDQ22	C (LVDS)*	PL34B	7	LDQ32	C (LVDS)*	
M1	PL25A	7	PCLKT7_0/LDQ22	T	PL35A	7	PCLKT7_0/LDQ32	T	
GNDIO	GNDIO7	-			GNDIO7	-			
M2	PL25B	7	PCLKC7_0/LDQ22	C	PL35B	7	PCLKC7_0/LDQ32	C	
M6	PL27A	6	PCLKT6_0	T (LVDS)*	PL37A	6	PCLKT6_0	T (LVDS)*	
M5	PL27B	6	PCLKC6_0	C (LVDS)*	PL37B	6	PCLKC6_0	C (LVDS)*	
M3	PL28A	6	VREF2_6	T	PL38A	6	VREF2_6	T	
M4	PL28B	6	VREF1_6	C	PL38B	6	VREF1_6	C	
VCCIO	VCCIO6	6			VCCIO6	6			
N7	PL31A	6	LLM1_SPLLT_IN_A	T (LVDS)*	PL41A	6	LLM2_SPLLT_IN_A	T (LVDS)*	
GNDIO	GNDIO6	-			GNDIO6	-			
N6	PL31B	6	LLM1_SPLLC_IN_A	C (LVDS)*	PL41B	6	LLM2_SPLLC_IN_A	C (LVDS)*	
N1	PL32A	6	LLM1_SPLLT_FB_A	T	PL42A	6	LLM2_SPLLT_FB_A	T	
N2	PL32B	6	LLM1_SPLLC_FB_A	C	PL42B	6	LLM2_SPLLC_FB_A	C	
VCCIO	VCCIO6	6			VCCIO6	6			
GNDIO	GNDIO6	-			GNDIO6	-			
P6	PL38A	6	LDQS38****	T (LVDS)*	PL48A	6	LDQS48****	T (LVDS)*	
N5	PL38B	6	LDQ38	C (LVDS)*	PL48B	6	LDQ48	C (LVDS)*	
P1	PL39A	6	LDQ38	T	PL49A	6	LDQ48	T	
VCCIO	VCCIO6	6			VCCIO6	6			
P2	PL39B	6	LDQ38	C	PL49B	6	LDQ48	C	
P3	PL40A	6	LDQ38	T (LVDS)*	PL50A	6	LDQ48	T (LVDS)*	
P4	PL40B	6	LDQ38	C (LVDS)*	PL50B	6	LDQ48	C (LVDS)*	
P5	PL41A	6	LDQ38	T	PL51A	6	LDQ48	T	
GNDIO	GNDIO6	-			GNDIO6	-			
P7	PL41B	6	LDQ38	C	PL51B	6	LDQ48	C	
R1	PL42A	6	LLM0_GPLLT_IN_A**	T (LVDS)*	PL57A	6	LLM0_GPLLT_IN_A**/LDQS57****	T (LVDS)*	
GNDIO	GNDIO6	-			GNDIO6	-			
R2	PL42B	6	LLM0_GPLLC_IN_A**	C (LVDS)*	PL57B	6	LLM0_GPLLC_IN_A**/LDQ57	C (LVDS)*	
R3	PL43A	6	LLM0_GPLLT_FB_A	T	PL58A	6	LLM0_GPLLT_FB_A/LDQ57	T	
R4	PL43B	6	LLM0_GPLLC_FB_A	C	PL58B	6	LLM0_GPLLC_FB_A/LDQ57	C	
VCCIO	VCCIO6	6			VCCIO6	6			
R6	PL44A	6	LLM0_GDLLT_IN_A**	T (LVDS)*	PL59A	6	LLM0_GDLLT_IN_A**/LDQ57	T (LVDS)*	
R5	PL44B	6	LLM0_GDLLC_IN_A**	C (LVDS)*	PL59B	6	LLM0_GDLLC_IN_A**/LDQ57	C (LVDS)*	
T1	PL45A	6	LLM0_GDLLT_FB_A	T	PL60A	6	LLM0_GDLLT_FB_A/LDQ57	T	
T2	PL45B	6	LLM0_GDLLC_FB_A	C	PL60B	6	LLM0_GDLLC_FB_A/LDQ57	C	
GNDIO	GNDIO6	-			GNDIO6	-			
R7	LLM0_PLLCAP	6			LLM0_PLLCAP	6			
T6	PL47A	6	LDQ51	T (LVDS)*	PL62A	6	LDQ66	T (LVDS)*	
T7	PL47B	6	LDQ51	C (LVDS)*	PL62B	6	LDQ66	C (LVDS)*	
U1	PL48A	6	LDQ51	T	PL63A	6	LDQ66	T	
U2	PL48B	6	LDQ51	C	PL63B	6	LDQ66	C	
VCCIO	VCCIO6	6			VCCIO6	6			
T3	PL49A	6	LDQ51	T (LVDS)*	PL64A	6	LDQ66	T (LVDS)*	
U3	PL49B	6	LDQ51	C (LVDS)*	PL64B	6	LDQ66	C (LVDS)*	
U6	PL50A	6	LDQ51	T	NC	-			
U5	PL50B	6	LDQ51	C	PL65B	6	LDQ66	C	
GNDIO	GNDIO6	-			GNDIO6	-			

**LFE2M35E/SE and LFE2M50E/SE Logic Signal Connections: 672 fpBGA  
 (Cont.)**

LFE2M35E/SE					LFE2M50E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
P8	PL45A	6	LDQ48	T	PL49A	6	LDQ52	T	
R6	PL45B	6	LDQ48	C	PL49B	6	LDQ52	C	
VCCIO	VCCIO6	6			VCCIO6	6			
T1	PL46A	6	LDQ48	T (LVDS)*	PL50A	6	LDQ52	T*	
U1	PL46B	6	LDQ48	C (LVDS)*	PL50B	6	LDQ52	C*	
R7	PL47A	6	LDQ48	T	PL51A	6	LDQ52	T	
T5	PL47B	6	LDQ48	C	PL51B	6	LDQ52	C	
GNDIO	GNDIO6	-			GNDIO6	-			
U3	PL48A	6	LDQS48	T (LVDS)*	PL52A	6	LDQS52	T*	
U4	PL48B	6	LDQ48	C (LVDS)*	PL52B	6	LDQ52	C*	
U5	PL49A	6	LDQ48	T	PL53A	6	LDQ52	T	
VCCIO	VCCIO6	6			VCCIO6	6			
U6	PL49B	6	LDQ48	C	PL53B	6	LDQ52	C	
U2	PL50A	6	LDQ48	T (LVDS)*	PL54A	6	LDQ52	T*	
V1	PL50B	6	LDQ48	C (LVDS)*	PL54B	6	LDQ52	C*	
W2	PL51A	6	LDQ48	T	PL55A	6	LDQ52	T	
GNDIO	GNDIO6	-			GNDIO6	-			
V2	PL51B	6	LDQ48	C	PL55B	6	LDQ52	C	
V4	PL55A	6	LDQ57	T (LVDS)*	PL59A	6		T*	
VCCIO	VCCIO6	6			VCCIO6	6			
V3	PL55B	6	LDQ57	C (LVDS)*	PL59B	6		C*	
-	-	-			GNDIO6	-			
W4	PL57A	6	LLM0_GPLLT_IN_A**/LDQS57****	T (LVDS)*	PL62A	6	LLM0_GPLLT_IN_A	T*	
GNDIO	GNDIO6	-			GNDIO6	-			
W3	PL57B	6	LLM0_GPLLC_IN_A**/LDQ57	C (LVDS)*	PL62B	6	LLM0_GPLLC_IN_A	C*	
W1	PL58A	6	LLM0_GPLLT_FB_A/LDQ57	T	PL63A	6	LLM0_GPLLT_FB_A	T	
Y1	PL58B	6	LLM0_GPLLC_FB_A/LDQ57	C	PL63B	6	LLM0_GPLLC_FB_A	C	
VCCIO	VCCIO6	6			VCCIO6	6			
AA1	PL59A	6	LLM0_GDLLT_IN_A**/LDQ57	T (LVDS)*	PL64A	6	LLM0_GDLLT_IN_A	T*	
AB1	PL59B	6	LLM0_GDLLC_IN_A**/LDQ57	C (LVDS)*	PL64B	6	LLM0_GDLLC_IN_A	C*	
U7	PL60A	6	LLM0_GDLLT_FB_A/LDQ57	T	PL65A	6	LLM0_GDLLT_FB_A	T	
V6	PL60B	6	LLM0_GDLLC_FB_A/LDQ57	C	PL65B	6	LLM0_GDLLC_FB_A	C	
GNDIO	GNDIO6	-			GNDIO6	-			
T8	LLM0_PLCCAP	6			LLM0_PLCCAP	6			
W5	PL62A	6	LDQ66	T (LVDS)*	PL67A	6	LDQ71	T*	
Y4	PL62B	6	LDQ66	C (LVDS)*	PL67B	6	LDQ71	C*	
U8	PL63A	6	LDQ66	T	PL68A	6	LDQ71	T	
W6	PL63B	6	LDQ66	C	PL68B	6	LDQ71	C	
VCCIO	VCCIO6	6			VCCIO6	6			
Y3	PL64A	6	LDQ66	T (LVDS)*	PL69A	6	LDQ71	T*	
AA3	PL64B	6	LDQ66	C (LVDS)*	PL69B	6	LDQ71	C*	
V7	NC	-			PL70A	6	LDQ71	T	
Y5	PL65B	6	LDQ66	C	PL70B	6	LDQ71	C	
GNDIO	GNDIO6	-			GNDIO6	-			
AB2	PL66A	6	LDQS66	T (LVDS)*	PL71A	6	LDQS71	T*	
AA4	PL66B	6	LDQ66	C (LVDS)*	PL71B	6	LDQ71	C*	
Y6	PL67A	6	LDQ66	T	PL72A	6	LDQ71	T	
VCCIO	VCCIO6	6			VCCIO6	6			

**LFE2M50E/SE and LFE2M70E/SE Logic Signal Connections: 900 fpBGA**  
**(Cont.)**

LFE2M50E/SE					LFE2M70E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential	
T2	PL45B	6	LLM3_SPLLC_IN_A	C (LVDS)*	PL57B	6	LLM3_SPLLC_IN_A/LDQ55	C (LVDS)*	
U9	PL46A	6	LLM3_SPLLT_FB_A	T	PL58A	6	LLM3_SPLLT_FB_A/LDQ55	T	
U8	PL46B	6	LLM3_SPLLC_FB_A	C	PL58B	6	LLM3_SPLLC_FB_A/LDQ55	C	
VCCIO	VCCIO6	6			GNDIO6	-			
U5	PL48A	6	LDQ52	T (LVDS)*	PL60A	6	LDQ64	T (LVDS)*	
U4	PL48B	6	LDQ52	C (LVDS)*	PL60B	6	LDQ64	C (LVDS)*	
V9	PL49A	6	LDQ52	T	PL61A	6	LDQ64	T	
V7	PL49B	6	LDQ52	C	PL61B	6	LDQ64	C	
VCCIO	VCCIO6	6			VCCIO6	6			
U3	PL50A	6	LDQ52	T (LVDS)*	PL62A	6	LDQ64	T (LVDS)*	
U2	PL50B	6	LDQ52	C (LVDS)*	PL62B	6	LDQ64	C (LVDS)*	
V8	PL51A	6	LDQ52	T	PL63A	6	LDQ64	T	
U6	PL51B	6	LDQ52	C	PL63B	6	LDQ64	C	
GNDIO	GNDIO6	-			GNDIO6	-			
U1	PL52A	6	LDQS52	T (LVDS)*	PL64A	6	LDQS64	T (LVDS)*	
V2	PL52B	6	LDQ52	C (LVDS)*	PL64B	6	LDQ64	C (LVDS)*	
V5	PL53A	6	LDQ52	T	PL65A	6	LDQ64	T	
VCCIO	VCCIO6	6			VCCIO6	6			
V6	PL53B	6	LDQ52	C	PL65B	6	LDQ64	C	
V1	PL54A	6	LDQ52	T (LVDS)*	PL66A	6	LDQ64	T (LVDS)*	
W1	PL54B	6	LDQ52	C (LVDS)*	PL66B	6	LDQ64	C (LVDS)*	
W5	PL55A	6	LDQ52	T	PL67A	6	LDQ64	T	
GNDIO	GNDIO6	-			GNDIO6	-			
W6	PL55B	6	LDQ52	C	PL67B	6	LDQ64	C	
W3	PL57A	6		T (LVDS)*	PL69A	6	LDQ73	T (LVDS)*	
W4	PL57B	6		C (LVDS)*	PL69B	6	LDQ73	C (LVDS)*	
W2	PL58A	6		T	PL70A	6	LDQ73	T	
Y4	PL58B	6		C	PL70B	6	LDQ73	C	
Y1	PL59A	6		T (LVDS)*	PL71A	6	LDQ73	T (LVDS)*	
VCCIO	VCCIO6	6			VCCIO6	6			
Y2	PL59B	6		C (LVDS)*	PL71B	6	LDQ73	C (LVDS)*	
Y5	PL60A	6		T	PL72A	6	LDQ73	T	
Y6	PL60B	6		C	PL72B	6	LDQ73	C	
AA1	NC	-			PL73A	6	LDQS73	T (LVDS)*	
GNDIO	GNDIO6	-			GNDIO6	-			
AA2	NC	-			PL73B	6	LDQ73	C (LVDS)*	
Y3	NC	-			PL74A	6	LDQ73	T	
AB1	NC	-			PL74B	6	LDQ73	C	
-	-	-			VCCIO6	6			
Y9	NC	-			PL75A	6	LDQ73	T (LVDS)*	
Y8	NC	-			PL75B	6	LDQ73	C (LVDS)*	
Y7	NC	-			PL76A	6	LDQ73	T	
AA7	NC	-			PL76B	6	LDQ73	C	
-	-	-			GNDIO6	-			
-	-	-			-	-			
AB2	NC	-			PL78A	6	LDQ82	T (LVDS)*	
AB3	NC	-			PL78B	6	LDQ82	C (LVDS)*	
AA5	NC	-			PL79A	6	LDQ82	T	

**LFE2M100E/SE Logic Signal Connections: 900 fpBGA (Cont.)**

LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential
U15	GND	-		
U16	GND	-		
U17	GND	-		
U18	GND	-		
U20	GND	-		
V14	GND	-		
V15	GND	-		
V16	GND	-		
V17	GND	-		
V27	GND	-		
V4	GND	-		
W23	GND	-		
W8	GND	-		
Y14	GND	-		
Y15	GND	-		
Y16	GND	-		
Y17	GND	-		
AA26	NC	-		
AB10	NC	-		
AB11	NC	-		
AB12	NC	-		
AB13	NC	-		
AB14	NC	-		
AB15	NC	-		
AB16	NC	-		
AB17	NC	-		
AB19	NC	-		
AB20	NC	-		
AB21	NC	-		
AB9	NC	-		
AC10	NC	-		
AC11	NC	-		
AC21	NC	-		
AC22	NC	-		
AC8	NC	-		
AC9	NC	-		
AD21	NC	-		
AD22	NC	-		
AD4	NC	-		
AD5	NC	-		
AD6	NC	-		
AD7	NC	-		
AD8	NC	-		

**LFE2M70E/SE and LFE2M100E/SE Logic Signal Connections: 1152 fpBGA**

LFE2M70E/SE				LFE2M100E/SE				
Ball Number	Ball/Pad Function	Bank	Dual Function	Differential	Ball/Pad Function	Bank	Dual Function	Differential
VCCIO	VCCIO7	7			VCCIO7	7		
F4	PL9A	7	VREF2_7	T	PL9A	7	VREF2_7	T
F3	PL9B	7	VREF1_7	C	PL9B	7	VREF1_7	C
GNDIO	GNDIO7	-			GNDIO7	-		
E1	PL11A	7	LUM0_SPLLT_IN_A/LDQ15	T (LVDS)*	PL11A	7	LUM0_SPLLT_IN_A/LDQ15	T (LVDS)*
E2	PL11B	7	LUM0_SPLLC_IN_A/LDQ15	C (LVDS)*	PL11B	7	LUM0_SPLLC_IN_A/LDQ15	C (LVDS)*
K9	PL12A	7	LUM0_SPLLT_FB_A/LDQ15	T	PL12A	7	LUM0_SPLLT_FB_A/LDQ15	T
H7	PL12B	7	LUM0_SPLLC_FB_A/LDQ15	C	PL12B	7	LUM0_SPLLC_FB_A/LDQ15	C
VCCIO	VCCIO7	7			VCCIO7	7		
F1	PL13A	7	LDQ15	T (LVDS)*	PL13A	7	LDQ15	T (LVDS)*
F2	PL13B	7	LDQ15	C (LVDS)*	PL13B	7	LDQ15	C (LVDS)*
J8	PL14A	7	LDQ15	T	PL14A	7	LDQ15	T
H6	PL14B	7	LDQ15	C	PL14B	7	LDQ15	C
GNDIO	GNDIO7	-			GNDIO7	-		
G2	PL15A	7	LDQS15	T (LVDS)*	PL15A	7	LDQS15	T (LVDS)*
G1	PL15B	7	LDQ15	C (LVDS)*	PL15B	7	LDQ15	C (LVDS)*
J7	PL16A	7	LDQ15	T	PL16A	7	LDQ15	T
VCCIO	VCCIO7	7			VCCIO7	7		
L8	PL16B	7	LDQ15	C	PL16B	7	LDQ15	C
L9	PL17A	7	LDQ15	T (LVDS)*	PL17A	7	LDQ15	T (LVDS)*
L10	PL17B	7	LDQ15	C (LVDS)*	PL17B	7	LDQ15	C (LVDS)*
H5	PL18A	7	LDQ15	T	PL18A	7	LDQ15	T
GNDIO	GNDIO7	-			GNDIO7	-		
J6	PL18B	7	LDQ15	C	PL18B	7	LDQ15	C
H2	NC	-			PL19A	7	LDQ23	T (LVDS)*
H1	NC	-			PL19B	7	LDQ23	C (LVDS)*
G5	NC	-			PL20A	7	LDQ23	T
G6	NC	-			PL20B	7	LDQ23	C
M9	NC	-			PL21A	7	LDQ23	T (LVDS)*
-	-	-			VCCIO7	7		
M10	NC	-			PL21B	7	LDQ23	C (LVDS)*
H3	NC	-			PL22A	7	LDQ23	T
H4	NC	-			PL22B	7	LDQ23	C
J2	PL19A	7		T (LVDS)*	PL23A	7	LDQS23	T (LVDS)*
-	-	-			GNDIO7	-		
J1	PL19B	7		C (LVDS)*	PL23B	7	LDQ23	C (LVDS)*
K2	PL20A	7		T	PL24A	7	LDQ23	T
K1	PL20B	7		C	PL24B	7	LDQ23	C
VCCIO	VCCIO7	7			VCCIO7	7		
J4	PL21A	7		T (LVDS)*	PL25A	7	LDQ23	T (LVDS)*
J3	PL21B	7		C (LVDS)*	PL25B	7	LDQ23	C (LVDS)*
J5	PL22A	7		T	PL26A	7	LDQ23	T
K5	PL22B	7		C	PL26B	7	LDQ23	C
GNDIO	GNDIO7	-			GNDIO7	-		
L2	PL24A	7	LDQ28	T (LVDS)*	PL28A	7	LDQ32	T (LVDS)*
L1	PL24B	7	LDQ28	C (LVDS)*	PL28B	7	LDQ32	C (LVDS)*
L7	PL25A	7	LDQ28	T	PL29A	7	LDQ32	T
K6	PL25B	7	LDQ28	C	PL29B	7	LDQ32	C
VCCIO	VCCIO7	7			VCCIO7	7		

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35E-5F484C	331	1.2V	-5	fpBGA	484	COM	35
LFE2-35E-6F484C	331	1.2V	-6	fpBGA	484	COM	35
LFE2-35E-7F484C	331	1.2V	-7	fpBGA	484	COM	35
LFE2-35E-5F672C	450	1.2V	-5	fpBGA	672	COM	35
LFE2-35E-6F672C	450	1.2V	-6	fpBGA	672	COM	35
LFE2-35E-7F672C	450	1.2V	-7	fpBGA	672	COM	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50E-5F484C	339	1.2V	-5	fpBGA	484	COM	50
LFE2-50E-6F484C	339	1.2V	-6	fpBGA	484	COM	50
LFE2-50E-7F484C	339	1.2V	-7	fpBGA	484	COM	50
LFE2-50E-5F672C	500	1.2V	-5	fpBGA	672	COM	50
LFE2-50E-6F672C	500	1.2V	-6	fpBGA	672	COM	50
LFE2-50E-7F672C	500	1.2V	-7	fpBGA	672	COM	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70E-5F672C	500	1.2V	-5	fpBGA	672	COM	70
LFE2-70E-6F672C	500	1.2V	-6	fpBGA	672	COM	70
LFE2-70E-7F672C	500	1.2V	-7	fpBGA	672	COM	70
LFE2-70E-5F900C	583	1.2V	-5	fpBGA	900	COM	70
LFE2-70E-6F900C	583	1.2V	-6	fpBGA	900	COM	70
LFE2-70E-7F900C	583	1.2V	-7	fpBGA	900	COM	70

### Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6E-5T144I	90	1.2V	-5	TQFP	144	IND	6
LFE2-6E-6T144I	90	1.2V	-6	TQFP	144	IND	6
LFE2-6E-5F256I	190	1.2V	-5	fpBGA	256	IND	6
LFE2-6E-6F256I	190	1.2V	-6	fpBGA	256	IND	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12E-5T144I	93	1.2V	-5	TQFP	144	IND	12
LFE2-12E-6T144I	93	1.2V	-6	TQFP	144	IND	12
LFE2-12E-5Q208I	131	1.2V	-5	PQFP	208	IND	12
LFE2-12E-6Q208I	131	1.2V	-6	PQFP	208	IND	12
LFE2-12E-5F256I	193	1.2V	-5	fpBGA	256	IND	12
LFE2-12E-6F256I	193	1.2V	-6	fpBGA	256	IND	12
LFE2-12E-5F484I	297	1.2V	-5	fpBGA	484	IND	12
LFE2-12E-6F484I	297	1.2V	-6	fpBGA	484	IND	12

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-35E-5FN484C	331	1.2V	-5	Lead-Free fpBGA	484	COM	35
LFE2-35E-6FN484C	331	1.2V	-6	Lead-Free fpBGA	484	COM	35
LFE2-35E-7FN484C	331	1.2V	-7	Lead-Free fpBGA	484	COM	35
LFE2-35E-5FN672C	450	1.2V	-5	Lead-Free fpBGA	672	COM	35
LFE2-35E-6FN672C	450	1.2V	-6	Lead-Free fpBGA	672	COM	35
LFE2-35E-7FN672C	450	1.2V	-7	Lead-Free fpBGA	672	COM	35

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-50E-5FN484C	339	1.2V	-5	Lead-Free fpBGA	484	COM	50
LFE2-50E-6FN484C	339	1.2V	-6	Lead-Free fpBGA	484	COM	50
LFE2-50E-7FN484C	339	1.2V	-7	Lead-Free fpBGA	484	COM	50
LFE2-50E-5FN672C	500	1.2V	-5	Lead-Free fpBGA	672	COM	50
LFE2-50E-6FN672C	500	1.2V	-6	Lead-Free fpBGA	672	COM	50
LFE2-50E-7FN672C	500	1.2V	-7	Lead-Free fpBGA	672	COM	50

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-70E-5FN672C	500	1.2V	-5	Lead-Free fpBGA	672	COM	70
LFE2-70E-6FN672C	500	1.2V	-6	Lead-Free fpBGA	672	COM	70
LFE2-70E-7FN672C	500	1.2V	-7	Lead-Free fpBGA	672	COM	70
LFE2-70E-5FN900C	583	1.2V	-5	Lead-Free fpBGA	900	COM	70
LFE2-70E-6FN900C	583	1.2V	-6	Lead-Free fpBGA	900	COM	70
LFE2-70E-7FN900C	583	1.2V	-7	Lead-Free fpBGA	900	COM	70

### Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-6E-5TN144I	90	1.2V	-5	Lead-Free TQFP	144	IND	6
LFE2-6E-6TN144I	90	1.2V	-6	Lead-Free TQFP	144	IND	6
LFE2-6E-5FN256I	190	1.2V	-5	Lead-Free fpBGA	256	IND	6
LFE2-6E-6FN256I	190	1.2V	-6	Lead-Free fpBGA	256	IND	6

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs (K)
LFE2-12E-5TN144I	93	1.2V	-5	Lead-Free TQFP	144	IND	12
LFE2-12E-6TN144I	93	1.2V	-6	Lead-Free TQFP	144	IND	12
LFE2-12E-5QN208I	131	1.2V	-5	Lead-Free PQFP	208	IND	12
LFE2-12E-6QN208I	131	1.2V	-6	Lead-Free PQFP	208	IND	12
LFE2-12E-5FN256I	193	1.2V	-5	Lead-Free fpBGA	256	IND	12
LFE2-12E-6FN256I	193	1.2V	-6	Lead-Free fpBGA	256	IND	12
LFE2-12E-5FN484I	297	1.2V	-5	Lead-Free fpBGA	484	IND	12
LFE2-12E-6FN484I	297	1.2V	-6	Lead-Free fpBGA	484	IND	12



# LatticeECP2/M Family Data Sheet

## Revision History

September 2013

Data Sheet DS1006

Date	Version	Section	Change Summary
February 2006	01.0	—	Initial release.
August 2006	01.1	Introduction	Updated Table 1-1 "LatticeECP2 Family Selection Guide".
			Architecture
		Updated Figure 2-13 "Secondary Clock Regions ECP2-50".	
		Updated Figure 2-25 "PIC Diagram".	
		Updated Figure 2-26 "Input Register Block for Left, Right and Bottom Edges".	
		Updated Figure 2-28 "Output Register Block for Left, Right and Bottom Edges".	
		Updated Figure 2-30 "DQS Input Routing for Left and Right Edges".	
		Updated Figure 2-32 "Edge Clock, DLL Calibration and DQS Local Bus Distribution".	
		Table 2-15 Selectable Master Clock (CCLK) Frequencies - Removed frequencies 15, 20, 21, 22, 23, 30, 34, 41, 45, 51, 55, 60.	
		Replaced "CLKINDEL" with "CLKO".	
		Updated SED section.	
		Qualified device migration capability when using DQS banks for DDR interfaces.	
		DC and Switching Characteristics	Added VCCPLL to the Recommended Operating Conditions table.
			Removed note 5 from "Hot Specifications" section.
			Added notes 7 and 8 to "Initialization Supply" Current table.
			Change note 6 - "...down to 95MHz" to "...down to 95MHz for DDR and 133MHz for DDR2" .
			New "Typical Building Block Function Performance" numbers.
			New External Switching Characteristics numbers.
			New Internal Switching Characteristics numbers.
			New Family Timing Adders numbers.
			Updated Timings for GPLLs, SPLs and DLLs.
			Added sysCONFIG waveforms.
		Remove HSTL15D_II from sysIO Recommended Operating Conditions table.	
		Updated Supply and Initialization Currents for ECP2-50.	
		Pinout Information	Added VCCPLL to the Signal Descriptions table.
			Updated Logic Signal Connections tables to include 484-fpBGA for the ECP2-50.
			Added Logic Signal Connections tables for ECP2-12 devices.
Updated Pin Information Summary table to include ECP2-12.			
Updated Power Supply and NC Connections table to include ECP2-12.			
Added note 2 to DDR Strobe (DQS) Pin table.			
Added Information on: PCI, DDR & SPI4.2 Capabilities of the device-Package combination.			

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